



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{SSS}	Rss(on) Typ	Is max TA = +25°C
12V	2.3 mΩ @ V _{GS} = 3.8V	20.2A

Description

This new generation MOSFET is designed to minimize the on-state resistance (Rss(on)) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- · Battery Management
- Load Switch
- Battery Protection

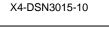
Features

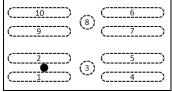
- CSP with Footprint 2.98mm x 1.49mm
- Height = 0.11mm for Low Profile
- ESD Protection of Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Case: X4-DSN3015-10
- Terminal Connections: See Diagram Below
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu or NiAu. Solderable per MIL-STD-202, Method 208
- Weight: 0.0012 grams (Approximate)







Source 1: 1,2,4,5 Top View

Source 2: 6, 7, 9, 10 Gate 2: 8

Gate 1: 3 Source 2: 6, 7, 9, 10 OS1
Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN12M7UCA10-7	X4-DSN3015-10	5000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



 $\begin{array}{l} MF = Product\ Type\ Marking\ Code \\ YM = Date\ Code\ Marking \\ Y\ or\ \overline{Y} = Year\ (ex:\ G = 2019) \\ M\ or\ \overline{M} = Month\ (ex:\ 9 = September) \end{array}$

Date Code Key

Year	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	F	G	Н	ı	J	K	L	М	N	0	Р	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Source-Source Voltage	Vsss	12	V		
Gate-Source Voltage			Vgss	±8	V
	Steady	$T_A = +25^{\circ}C$		20.2	
Continuous Source Current (Note 5) V _{GS} = 4.5V	Is	16.1	Α		
0 " 0 0 (// 5) // 0.5//		13.6	Δ.		
Continuous Source Current (Note 5) V _{GS} = 2.5V	Is	10.8	Α		
Pulsed Source Current (Note 6)	I _{SM}	80	Α		

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7)	PD	0.74	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 7)	R _{θJA}	171.9	°C/W
Power Dissipation (Note 5)	PD	1.73	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	Reja	74.4	°C/W
Operating and Storage Temperature Range	T_{J}, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

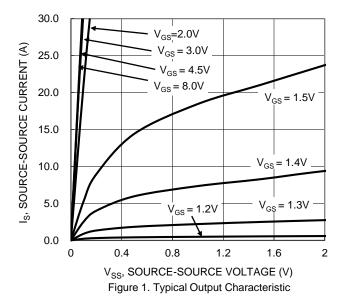
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)	, , ,	I	71				
Source-Source Breakdown Voltage	BVsss	12	_	_	V	$V_{GS} = 0V$, $I_S = 1mA$	
Zero Gate Voltage Drain Current TJ = +25°C	Isss	_	_	1	μΑ	Vss = 9.6V, Vgs = 0V	
Cata Cauraa Laakaga		_	_	±10	μΑ	Vgs = ±8V, Vss = 0V	
Gate-Source Leakage	IGSS	_	_	±1	μA	Vgs = ±5V, Vss = 0V	
ON CHARACTERISTICS (Note 8)						•	
Gate Threshold Voltage	V _{GS(TH)}	0.5	0.8	1.4	V	Vss = 10V, Is = 1.11mA	
		1.55	2.19	2.75		Vgs = 4.5V, Is = 6A	
Static Source-Source On-Resistance		1.6	2.30	2.85	0	Vgs = 3.8V, Is = 6A	
Static Source-Source On-Resistance	Rss(ON)	1.65	2.51	3.95	mΩ	Vgs = 3.1V, Is = 6A	
		1.9	2.93	6.1		V _G S = 2.5V, I _S = 6A	
Diode Forward Voltage	Vss	_	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 6A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	3039	_		101/11/	
Output Capacitance	Coss	_	530	_	pF	Vss = 10V, $Vgs = 0V$, $f = 1MHz$	
Reverse Transfer Capacitance	Crss	_	141	_			
Total Gate Charge	Qg	_	35.7	_			
Gate-Source Charge	Qgs	_	6.7	_	nC	Vss = 6V, Vgs = 4V,	
Gate-Drain Charge	Q _{gd}	_	9.2	_	IIC	I _S = 6A	
Gate Charge at V⊤н	Qg(th)	_	3.4	_			
Turn-On Delay Time	t _D (ON)	_	880	_			
Turn-On Rise Time	t _R	_	1468	_		$V_{SS} = 6V$, $V_{GS} = 4V$,	
Turn-Off Delay Time	tD(OFF)	_	2914	_	ns	Is = 6A	
Turn-Off Fall Time	tF	_	2830	_			

Notes:

- Device mounted on FR-4 material with 1inch² (6.45cm²), 2oz. (0.071mm thick) Cu.
 Repetitive rating, pulse width limited by junction temperature.
 Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to production testing.

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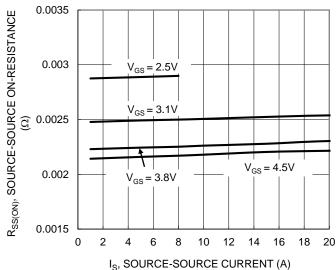


Figure 3. Typical On-Resistance vs. Source Current and Gate Voltage

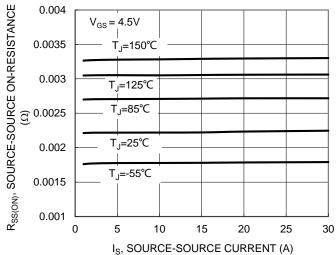


Figure 5. Typical On-Resistance vs. Source Current and Junction Temperature

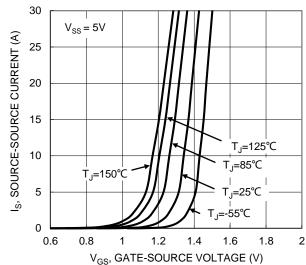


Figure 2. Typical Transfer Characteristic

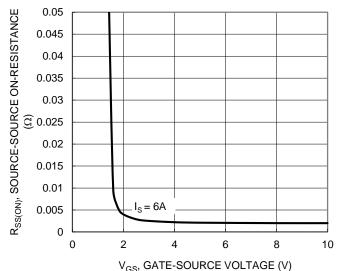


Figure 4. Typical Transfer Characteristic

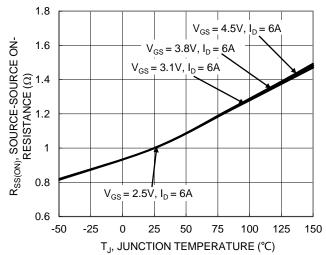


Figure 6. On-Resistance Variation with Junction Temperature



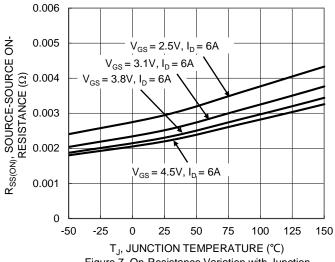


Figure 7. On-Resistance Variation with Junction Temperature

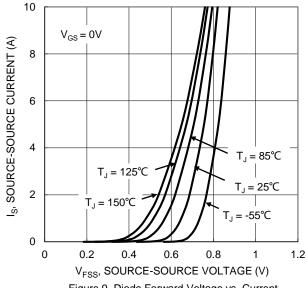


Figure 9. Diode Forward Voltage vs. Current

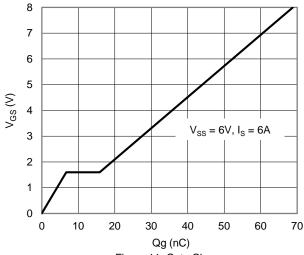


Figure 11. Gate Charge

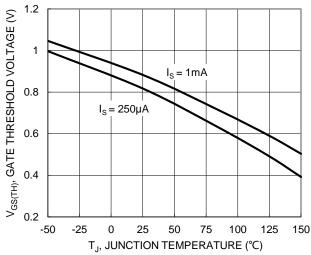
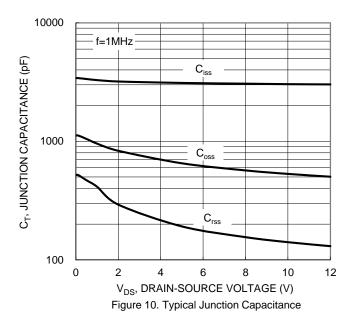
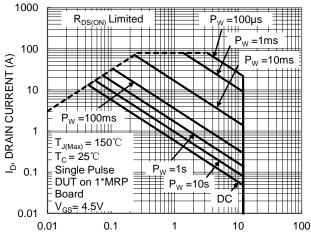


Figure 8. Gate Threshold Variation vs. Junction Temperature





 V_{DS} , DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



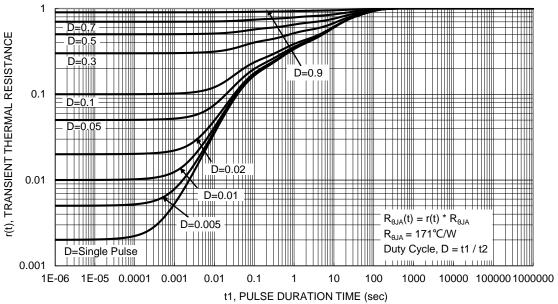


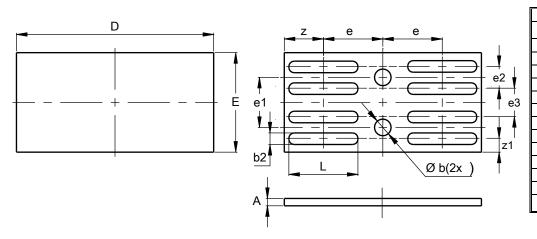
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X4-DSN3015-10

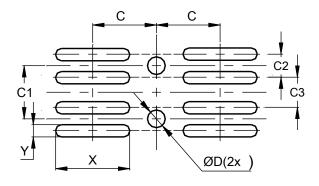


X4-DSN3015-10							
Dim	Min	Max	Тур				
Α	0.09	0.16	0.11				
b			0.25				
b2			0.175				
D	2.93	3.03	2.98				
Е	1.44	1.54	1.49				
е			0.895				
e1			0.75				
e2			0.325				
е3			0.425				
L			1.04				
Z			0.595				
z1			0.2075				
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X4-DSN3015-10



Dimensions	Value
Dimensions	(in mm)
С	0.895
C1	0.750
C2	0.325
C3	0.425
D	0.25
Х	1.04
Υ	0.175



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